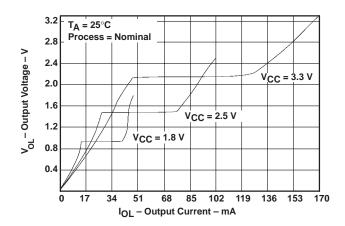
- Member of the Texas Instruments Widebus™ Family
- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- DOC[™] (Dynamic Output Control) Circuit Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation
- Less Than 2-ns Maximum Propagation Delay at 2.5-V and 3.3-V V_{CC}
- Dynamic Drive Capability Is Equivalent to Standard Outputs With I_{OH} and I_{OL} of ±24 mA at 2.5-V V_{CC}

- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- I_{off} Supports Partial-Power-Down Mode Operation
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic Thin Shrink Small-Outline (DGG) and Thin Very Small-Outline (DGV) Packages

description

A Dynamic Output Control (DOC) circuit is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical V_{OL} vs I_{OL} and V_{OH} vs I_{OH} curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to the TI application reports, AVC Logic Family Technology and Applications, literature number SCEA006, and Dynamic Output Control (DOCTM) Circuitry Technology and Applications, literature number SCEA009.



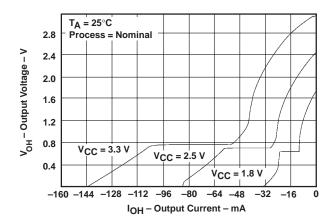


Figure 1. Output Voltage vs Output Current

This 16-bit (dual-octal) noninverting bus transceiver is operational at 1.2-V to 3.6-V V_{CC} , but is designed specifically for 1.65-V to 3.6-V V_{CC} operation.

The SN74AVCH16245 is designed for asynchronous communication between data buses. The control-function implementation minimizes external timing requirements.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the device so that the buses are effectively isolated.



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description (continued)

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The SN74AVCH16245 is characterized for operation from –40°C to 85°C.

terminal assignments

DGG OR DGV PACKAGE (TOP VIEW)

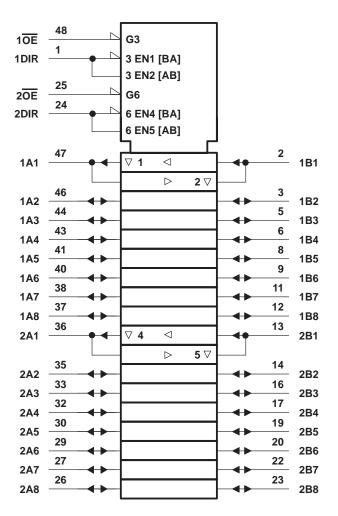
	(,	
			h —
1DIR L	1	48	10E
1B1 L	2	47	1A1
1B2	3	46	1A2
GND [4	45] GND
1B3 [5	44	1A3
1B4 [6	43	1A4
v _{cc} [7	42	
1B5 [8	41] 1A5
1B6 [9	40	1A6
GND [10	39	GND
1B7 [11	38] 1A7
1B8 [12	37	1A8
2B1 [13	36	2A1
2B2 [14	35	2A2
GND [15	34	GND
2B3 [16	33	2A3
2B4 [17	32	2A4
v _{cc} [18	31] v _{cc}
2B5	19	30	2A5
2B6 [20	29	2A6
GND [21	28	GND
2B7 [22	27	2A7
2B8 [23	26	2A8
2DIR	24	25	2 <u>OE</u>
			ı

FUNCTION TABLE (each 8-bit transceiver)

INP	UTS	OPERATION
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	Χ	Isolation

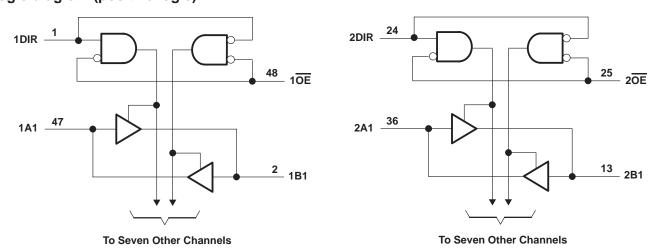


logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





SN74AVCH16245 16-BIT BUS TRANSCEIVER WITH 3-STATE OUTPUTS

SCES151D - DECEMBER 1998 - REVISED DECEMBER 1999

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC} –0.5 V to 4.6 V
Input voltage range, V _I : Except I/O ports (see Note 1)
I/O ports (see Notes 1 and 2)
Voltage range applied to any input/output
when the output is in the high-impedance or power-off state, VO (see Note 1)0.5 V to 4.6 V
Voltage range applied to any input/output
when the output is in the high or low state, V _O (see Notes 1 and 2)0.5 V to V _{CC} + 0.5 V
Input clamp current, $I_{ K }(V_{ I } < 0)$
Output clamp current, I _{OK} (V _O < 0)
Continuous output current, IO ±50 mA
Continuous current through each V _{CC} or GND ±100 mA
Package thermal impedance, θ _{JA} (see Note 3): DGG package
DGV package 58°C/W
Storage temperature range, T _{sto}

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.



PRODUCT PREVIEW

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V/00	Supply voltage	Operating	1.4	3.6	V
VCC	Su pp iy voltage	Data retention only	1.2		V
		V _{CC} = 1.2 V	Vcc		
	High-level input voltage	$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$	0.65 × V _{CC}		
V_{IH}		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V _{CC}		V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	2		
		V _{CC} = 1.2 V		GND	
		V _{CC} = 1.4 V to 1.6 V		0.35 × V _{CC}	
V_{IL}	Low-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$	V
		V _{CC} = 2.3 V to 2.7 V		0.7	
		V _{CC} = 3 V to 3.6 V		0.8	
٧ _I	Input voltage		0	3.6	V
	Output voltage	Active state	0	Vcc	V
VO	Output voltage	3-state	0	3.6	v v
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		-2	
lavia	Static high-level output current [†]	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		-4	
IOHS	Static high-level output current	V _{CC} = 2.3 V to 2.7 V		-8	mA
		V _{CC} = 3 V to 3.6 V		-12	1
		V _{CC} = 1.4 V to 1.6 V		2	
lols	Charlie lave lavel autout average †	V _{CC} = 1.65 V to 1.95 V		4	mA
	Static low-level output current [†]	V _{CC} = 2.3 V to 2.7 V		8	
		V _{CC} = 3 V to 3.6 V		12	1
Δt/Δν	Input transition rise or fall rate	V _{CC} = 1.4 V to 3.6 V		5	ns/V
TA	Operating free-air temperature		-40	85	°C

To Dynamic drive capability is equivalent to standard outputs with I_{OH} and I_{OL} of ±24 mA at 2.5-V V_{CC}. See Figure 1 for V_{OL} vs I_{OL} and V_{OH} vs I_{OH} characteristics. Refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number **SCEA006**, and *Dynamic Output Control (DOC™) Circuitry Technology and Applications*, literature number **SCEA009**.

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

PRODUCT PREVIEW

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CO	ONDITIONS	Vcc	MIN	TYP [†]	MAX	UNIT	
		I _{OHS} = -100 μA		1.4 V to 3.6 V	V _{CC} -0.	2			
		$I_{OHS} = -2 \text{ mA},$	V _{IH} = 0.91 V	1.4 V	1.05				
Voн		$I_{OHS} = -4 \text{ mA},$	V _{IH} = 1.07 V	1.65 V	1.2			V	
		$I_{OHS} = -8 \text{ mA},$	V _{IH} = 1.7 V	2.3 V	1.75				
		$I_{OHS} = -12 \text{ mA},$	V _{IH} = 2 V	3 V	2.3				
		I _{OLS} = 100 μA		1.4 V to 3.6 V			0.2		
		$I_{OLS} = 2 \text{ mA},$	V _{IL} = 0.49 V	1.4 V			0.4		
VOL		I _{OLS} = 4 mA,	V _{IL} = 0.57 V	1.65 V			0.45	V	
		$I_{OLS} = 8 \text{ mA},$	V _{IL} = 0.7 V	2.3 V			0.55		
		I _{OLS} = 12 mA,	V _{IL} = 0.8 V	3 V			0.7		
Ц	Control inputs	$V_I = V_{CC}$ or GND		3.6 V			±2.5	μΑ	
	-	V _I = 0.57 V		1.65 V	25				
I _{BHL} ‡		V _I = 0.7 V	V _I = 0.7 V 2.3 V					μΑ	
		V _I = 0.8 V		3 V	75				
		V _I = 1.07 V	V _I = 1.07 V						
IBHH		V _I = 1.7 V	V _I = 1.7 V		-45			μΑ	
1		V _I = 2 V		3 V	-75				
			V _I = 0 to V _{CC}		200			μА	
IBHLO	1	$V_I = 0$ to V_{CC}			300				
					500				
				1.95 V	-200				
Івнно) [#]	$V_I = 0$ to V_{CC}		2.7 V	-300			μΑ	
				3.6 V	-500				
l _{off}		V _I or V _O = 3.6 V		0			±10	μΑ	
IOZ		$V_O = V_{CC}$ or GND		3.6 V			±12.5	μΑ	
Icc		$V_I = V_{CC}$ or GND,	I _O = 0	3.6 V			40	μА	
C.	Control inputs	V. Vaaar CND						~F	
Ci	Control inputs	$V_I = V_{CC}$ or GND		3.3 V				pF	
C.	A or D porto	Name of the second		2.5 V				~ F	
C _{io}	A or B ports	$V_O = V_{CC}$ or GND		3.3 V		-		pF	

[†] Typical values are measured at T_A = 25°C.



[‡] The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

[§] The bus-hold circuit can source at least the minimum high sustaining current at VIH min. IBHH should be measured after raising VIN to VCC and then lowering it to VIH min.

 $[\]P$ An external driver must source at least IBHLO to switch this node from low to high.

[#] An external driver must sink at least I_{BHHO} to switch this node from high to low.

For I/O ports, the parameter IOZ includes the input leakage current.

PRODUCT PREVIEW

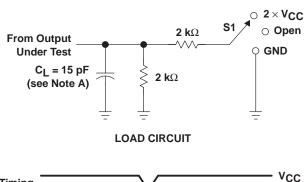
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 2 through 5)

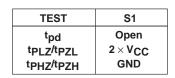
PARAMETER	PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.2 V	V _{CC} =	1.5 V 1 V	V _{CC} =		V _{CC} =		V _{CC} = ± 0.3		UNIT
	(1141 01)	(551761)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
t _{pd}	A or B	B or A										ns	
t _{en}	ŌĒ	A or B										ns	
t _{dis}	ŌĒ	A or B										ns	

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT	
		1E31 CONDITIONS	TYP	TYP	TYP	ONIT	
	Power dissipation	Outputs enabled	Cı = 0. f = 10 MHz				PΓ
Cpd	capacitance	Outputs disabled	$C_L = 0$, $f = 10 MHz$				þг

PARAMETER MEASUREMENT INFORMATION V_{CC} = 1.2 V AND 1.5 V \pm 0.1 V

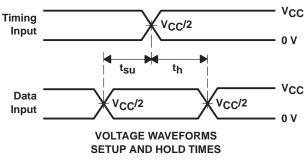


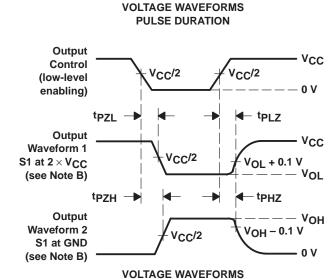


VCC

0 V

V_{CC}/2

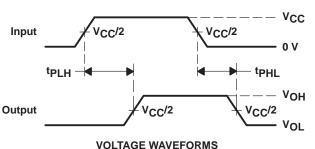




ENABLE AND DISABLE TIMES

V_{CC}/2

Input



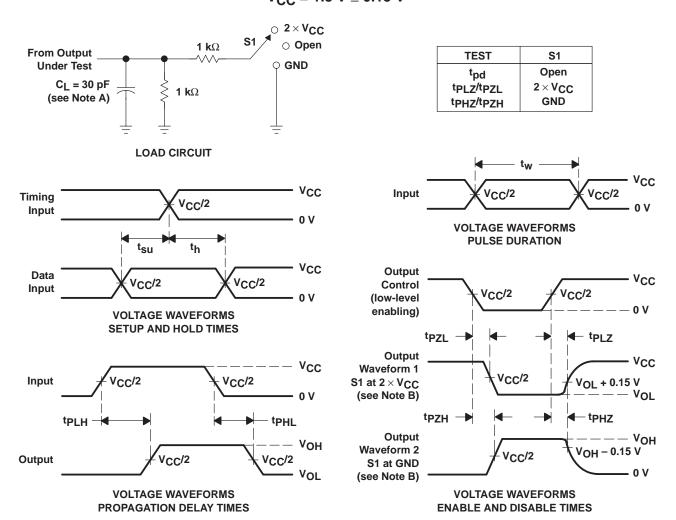
 $\label{eq:propagation delay times}$ NOTES: A. C1 includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \ \Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$

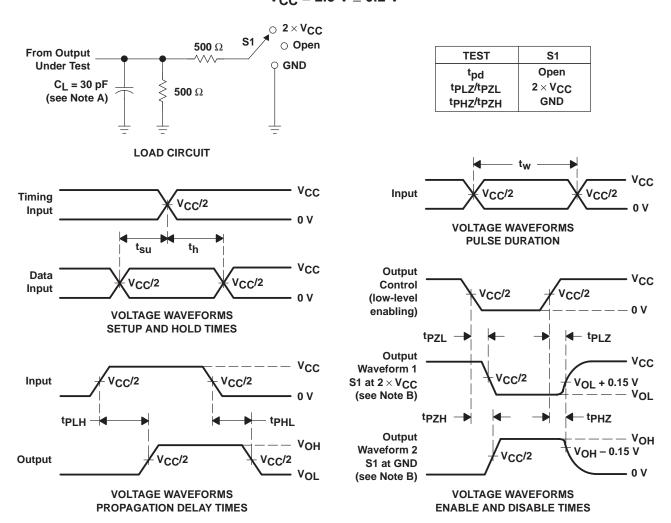


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2$ ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 V \pm 0.2 V$



NOTES: A. C_L includes probe and jig capacitance.

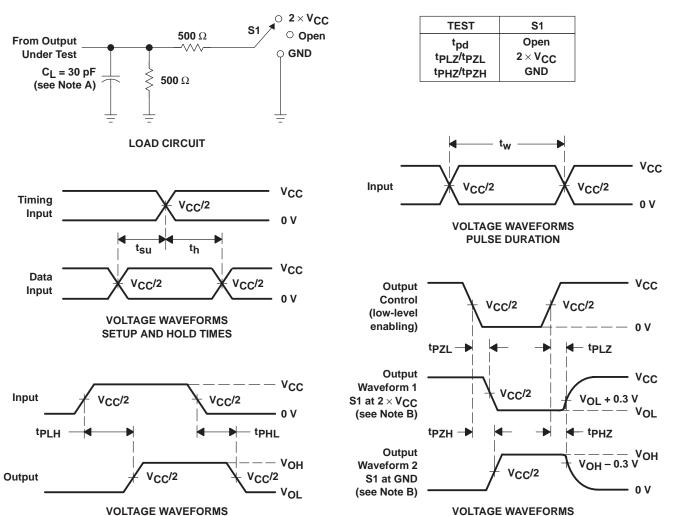
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpl H and tpHI are the same as tpd.

Figure 4. Load Circuit and Voltage Waveforms



ENABLE AND DISABLE TIMES

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$



- NOTES: A. C_I includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.

PROPAGATION DELAY TIMES

- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. tpLH and tpHL are the same as tpd.

Figure 5. Load Circuit and Voltage Waveforms

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